

ABSOLUTE MAXIMUM RATINGS

Table 3. REV H

Parameter	Rating
Drain Bias Voltage	4.5 V
RF Input Power	20 dBm
Gate Bias Voltage	
V_{GG1}	-2 V to +0.2 V
V_{GG2}	-2 V to +0.2 V
Continuous Power Dissipation, P_{DISS} ($T_A = 85^\circ\text{C}$, Derate 6.9 mW/ $^\circ\text{C}$ Above 85°C)	0.45 W
Channel Temperature	150$^\circ\text{C}$
Maximum Peak Reflow Temperature	260 $^\circ\text{C}$
Storage Temperature	-65 $^\circ\text{C}$ to +85 $^\circ\text{C}$
Operating Temperature	-40 $^\circ\text{C}$ to +85 $^\circ\text{C}$
ESD Sensitivity (Human Body Model)	Class 0, Passed 150 V

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL RESISTANCE

Thermal performance is directly linked to printed circuit board (PCB) design and operating environment. Careful attention to PCB thermal design is required.

Table 4. Thermal Resistance

Package Type ¹	θ_{JC}	Unit
HCP-16-1	144.8	$^\circ\text{C}/\text{W}$

¹Thermal impedance simulated values are based on JEDEC 2s2p thermal test board. See JEDEC JESD51.

ESD CAUTION



ESD (electrostatic discharge) sensitive device.

Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

ABSOLUTE MAXIMUM RATINGS

Table 3. REV I

Parameter	Rating
Drain Bias Voltage	4.5 V
RF Input Power	20 dBm
Gate Bias Voltage	
V_{GG1}	-2 V to +0.2 V
V_{GG2}	-2 V to +0.2 V
Continuous Power Dissipation, P_{DISS} ($T_A = 85^\circ\text{C}$, Derate 6.9 mW/ $^\circ\text{C}$ Above 85°C)	0.45 W
Channel Temperature	175$^\circ\text{C}$
Maximum Peak Reflow Temperature	260 $^\circ\text{C}$
Storage Temperature	-65 $^\circ\text{C}$ to +85 $^\circ\text{C}$
Operating Temperature	-40 $^\circ\text{C}$ to +85 $^\circ\text{C}$
ESD Sensitivity (Human Body Model)	Class 0, Passed 150 V

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